


**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	MDG/22/13034	
<b>1.3 Title of PCN</b>	STM32WB5x and STM32WB3x - product enhancement	
<b>1.4 Product Category</b>	STM32WB55Cx, STM32WB55Rx, STM32WB55Vx, STM32WB35Cx, STM32WB50x, STM32WB30Cx	
<b>1.5 Issue date</b>	2022-04-21	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	NEMETH KRISZTINA
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<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Ricardo Antonio DE SA EARP
<b>2.1.2 Marketing Manager</b>	Veronique BARLATIER
<b>2.1.3 Quality Manager</b>	Pascal NARCHE

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
General Product & Design	Die redesign : Mask or mask set change with new die design like metallization (specifically chip frontside) or bug fix	TSMC FAB14 (Taiwan)

**4. Description of change**

	Old	New
<b>4.1 Description</b>	<p>STM32WB55 and STM32WB35 STM32WB 1M - (Die495 - cut2.1 revision Y) product has limitation as described in Errata Sheet (ES0394 Rev9 / July 2021)</p> <ul style="list-style-type: none"> <li>- HSE Glitch, 2.2.19, 2.2.20,</li> <li>- SMPS Functionality 2.2.21</li> </ul> <p>STM32WB50 and STM32WB30 - (Die495 - cut2.1 revision Y) product has limitation as described in Errata Sheet (ES0492 - Rev4 - July 2021)</p> <ul style="list-style-type: none"> <li>- HSE Glitch, 2.2.15</li> </ul> <p>STM32WB5x and STM32WB3x Device Stack-up - Die protective layer over passivation material is PBO (Polybenzoxazole)</p>	<p>STM32WB55 and STM32WB35 - (Die495 - cut2.2 revision X) product fixes those limitations as described in Errata Sheet (ES0394 Rev11 / March 2022):</p> <ul style="list-style-type: none"> <li>- HSE Glitch in RF Digital/Analog IP is fixed (Note that AN5290 - rev6 describing how to improve tolerance to the glitch is not needed anymore).</li> <li>- SMPS start-up in Analog IP is fixed</li> </ul> <p>STM32WB50 and STM32WB30 - (Die495 - cut2.2 revision X) product fixes those limitations as described in Errata Sheet (ES0492 - Rev6 - March 2022):</p> <ul style="list-style-type: none"> <li>- HSE Glitch in RF Digital/Analog IP is fixed (Note that AN5290 - rev6 describing how to improve tolerance to the glitch is not needed anymore).</li> </ul> <p>STM32WB5x and STM32WB3x Device Stack-up - Die protective layer over passivation change from PBO to PI (Polyimide)</p>
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	functionality enhancement	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	Improvements was implemented to increase robustness, performances and quality of our products.
<b>5.2 Customer Benefit</b>	SERVICE IMPROVEMENT

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	Traceability ensured by ST internal tools. Die revision changes from "Y" to "X" on Package Marking
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2022-03-22
<b>7.2 Intended start of delivery</b>	2022-05-16
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	13034 Combined reports RER1613 V3.2 - RER1912 V2.pdf		
<b>8.2 Qualification report and qualification results</b>	Available (see attachment)	<b>Issue Date</b>	2022-04-21

**9. Attachments (additional documentations)**

13034 Public product.pdf  
13034 Combined reports RER1613 V3.2 - RER1912 V2.pdf  
13034 PCN13034\_Additional information.pdf

**10. Affected parts**

<b>10. 1 Current</b>		<b>10.2 New (if applicable)</b>
<b>10.1.1 Customer Part No</b>	<b>10.1.2 Supplier Part No</b>	<b>10.1.2 Supplier Part No</b>
	STM32WB30CEU5A	
	STM32WB35CCU6A	
	STM32WB35CCU7A	
	STM32WB35CEU6A	
	STM32WB50CGU5	
	STM32WB55CCU6	
	STM32WB55RCV6	
	STM32WB55RGV6	
	STM32WB55VGY6TR	
	STM32WB5MMGH6TR	

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